Amendments to the Specification:

On page 1 insert **TITLE OF THE INVENTION** before "Title: Improvement in and relating to edge grinding".

On page 1 replace ~~**Title: Improvement in and relating to edge grinding**~~ with **Improvement In and Relating to Edge Grinding**.

On page 1 replace ~~Field of the Invention~~ with **BACKGROUND OF THE INVENTION**.

On page 1 insert after the previously inserted "Background of the Invention" **(1) Field of the Invention**.

On page 1 replace ~~**Background to the Invention**~~ with **(2) Description of Related Art including information disclosed under 37 CFR 1.97 and 1.98.**

On page 3 replace ~~**Summary of the Invention**~~ with **BRIEF SUMMARY OF THE INVENTION**.

On page 9 insert before the first full paragraph **BRIEF DESCRIPTION OF THE SEVERAL VIEWS OF THE DRAWINGS**.

On page 10 replace ~~**Detailed description of drawings**~~ with **DETAILED DESCRIPTION OF THE INVENTION**.

Insert following the claims a new page including the following:

ABSTRACT OF THE DISCLOSURE

A method of positioning a grooved grinding wheel relative to a disc-like circular workpiece for edge grinding the workpiece using the groove in the wheel includes the steps of mounting the workpiece for rotation about a first axis, mounting the

grinding wheel for rotation about a second parallel axis, effecting relative movement between the workpiece and the wheel to engage the rim of the wheel within the groove and performing a preliminary grind. The wheel is then separated from the wafer and the peripheral rim of the wafer is measured to determine the accuracy of its form relative to a template or to stored data. The position of the wheel is axially adjusted in accordance with the measurements made on the profile of the rim produced by the preliminary grind, and the rim is ground again with a second preliminary grind with the grinding wheel located at the axially shifted position. The profile of the ground rim of the workpiece is measured as before, and the axial position of the grinding wheel is adjusted again. The steps of grinding and measuring the periphery of the workpiece is repeated until the rim profile possesses the desired accuracy. The final position of the grooved grinding wheel is then utilized for grinding future wafers.